



CeraDiode

SMD type, array, case size 1012

Series/Type:	CDA6C05GTH
Ordering code:	B72735D0050H062
Date:	2007-02-20
Version:	3

**Reliable ESD protection of multiple high-speed signal lines
1:1 drop-in replacement of SOT23-6L diode packages
without change of PCB layout.**



Description

Due to the ongoing miniaturization, today's electronic devices are more and more sensitive to electrostatic discharges (ESD). Therefore reliable protection components become absolutely necessary to safeguard your valuable electronics against the impact of ESD.

CeraDiodes are ceramic semiconductors optimized specifically for high performance in ESD applications. They have a non-linear voltage/current characteristic for effectively suppressing extremely fast voltage transients and offer superior parametric stability over the complete operating range of $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$.

CeraDiodes are bi-directional devices. A single CeraDiode connected from signal/data line to ground routes both positive and negative ESD transitions safely to the ground plane. This technique eliminates the need to route ESD charge into the power plane, possibly damaging nearby integrated circuits. CeraDiodes for high-speed lines exhibits a very low capacitance designed for maximum ESD protection combined with minimal signal distortion.

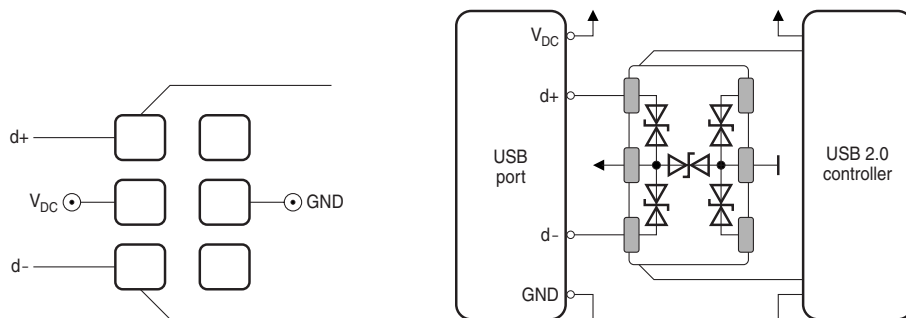
Features

- Bi-directional ESD protection to IEC 61000-4-2 (level 4)
- Suitable for uni- and bi-directional lines
- Bi-directional ESD protection of four data lines and one supply line in a 3-fold array
- Routes all ESD events, both positive and negative, safely to ground
- Suitable for DC working voltages up to 5.6 V
- Low capacitance: 10 pF maximum
- USB 2.0 compliant
- No derating of maximum ratings up to 85 °C
- Surface mount package in SOT23-6L case size (inch case size 1012)
- Extremely fast response time < 0.5 ns
- Lead-free nickel barrier terminations suitable for lead-free soldering
- RoHS-compatible

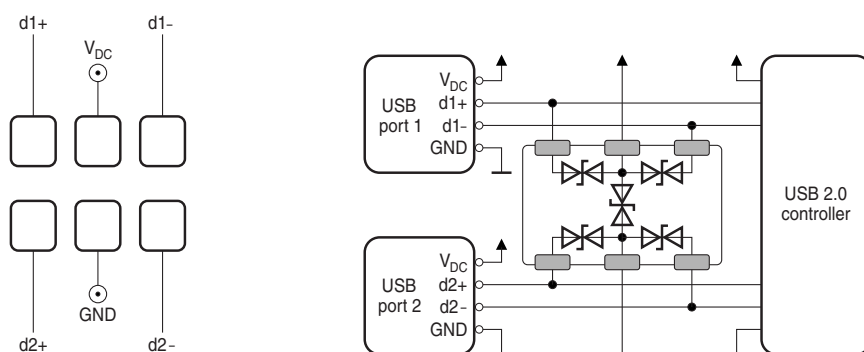
Applications

- Interfaces (e.g. USB, IEEE 1394, Ethernet)
- EDP products (e.g. desktop and notebook computers)
- Peripherals (e.g. printers, memory cards, etc.)
- Portable handheld products (e.g. PDA)
- Mobile communication
- Consumer products (Flat TVs, set top boxes, MP3 players, digital cameras, etc.)
- Liquid crystal displays (LCD) / monitors

Application examples

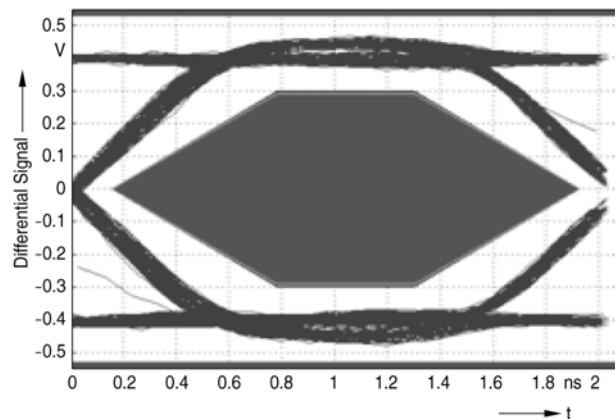


Note: USB 2.0 single port line protection with high-speed array CDA6C05GTA.



Note: USB 2.0 dual port line protection with high-speed array CDA6C05GTA.

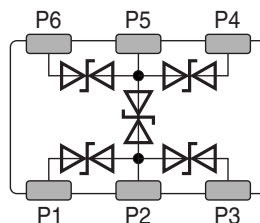
USB 2.0 compliance test



Note: USB 2.0 compliance test result of high-speed array CDA6C05GTA.

Pin configuration

Pin	Description
P1	I/O Line 1
P2	GND
P3	I/O Line 2
P4	I/O Line 3
P5	V_{DC}
P6	I/O Line 4



Due to the symmetrical configuration no marking information is needed. P2 and P5 can be interchanged. The part is also working without any V_{DC} supply.

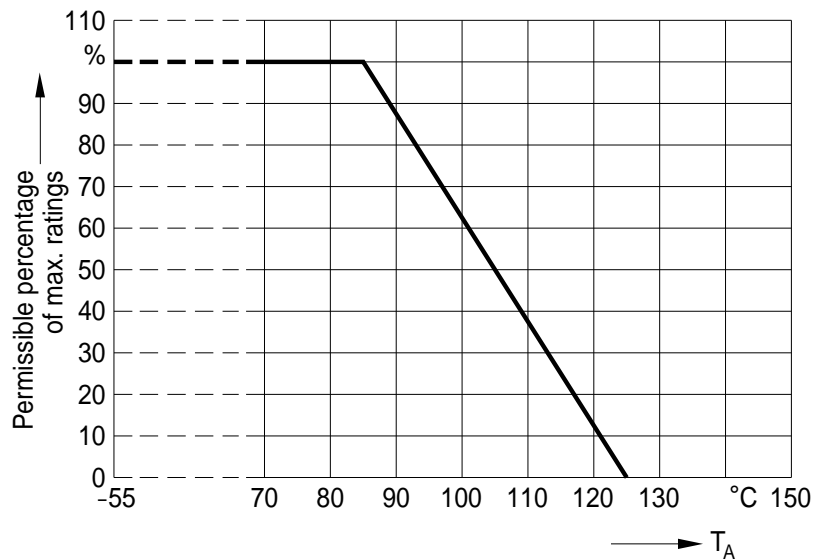
Maximum ratings ($T_A = 85\text{ }^\circ\text{C}$)

Rating	Symbol	Value	Unit
Maximum DC working voltage	V_{DC}	5.6	V
Peak current @ 8/20 μs (V_{DC} to GND)	I_{PP}	20	A
Air discharge ESD capability (to IEC 61000-4-2 method)	V_{ESD}	15	kV
Contact discharge ESD capability (to IEC 61000-4-2 method)	V_{ESD}	8	kV
Operating temperature (without derating)	T_{op}	-40 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +125	$^\circ\text{C}$

Characteristics ($T_A = 25\text{ °C}$)

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Unit
Breakdown voltage	V_{BR}	$I_{BR} = 1\text{ mA}$ (any I/O Pin to GND)	52	-	-	V
	V_{BR}	$I_{BR} = 1\text{ mA}$ (V_{DC} to GND)	14	-	-	V
Leakage current	I_{leak}	$V_{leak} = 5.6\text{ V}$	-	-	1	μA
Clamping voltage	V_{clamp}	$I_{PP} = 1\text{ A}$, 8/20 μs (any I/O Pin to GND)	-	-	195	V
	V_{clamp}	$I_{PP} = 1\text{ A}$, 8/20 μs (V_{DC} to GND)	-	-	40	V
Capacitance	C	$V = 1\text{ V}$, $f = 1\text{ MHz}$ (any I/O Pin to GND)	-	7	10	pF
	C	$V = 1\text{ V}$, $f = 1\text{ MHz}$ (Any I/O Pin to I/O Pin)	-	3.5	5	pF

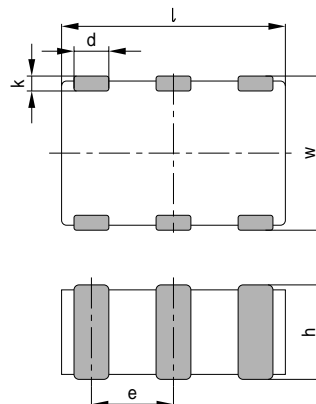
Note: Any operating voltage lower than 5.6 V results in lower leakage current.

Typical characteristics


Dimensional drawing

Dimensions in mm

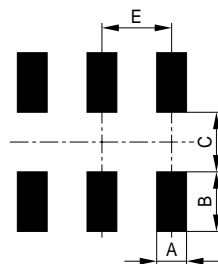
Symbol	Min.	Max.
l	2.90	3.50
w	2.25	2.75
h	-	1.2
d	0.35	0.65
e	0.8	1.1
k	-	0.45



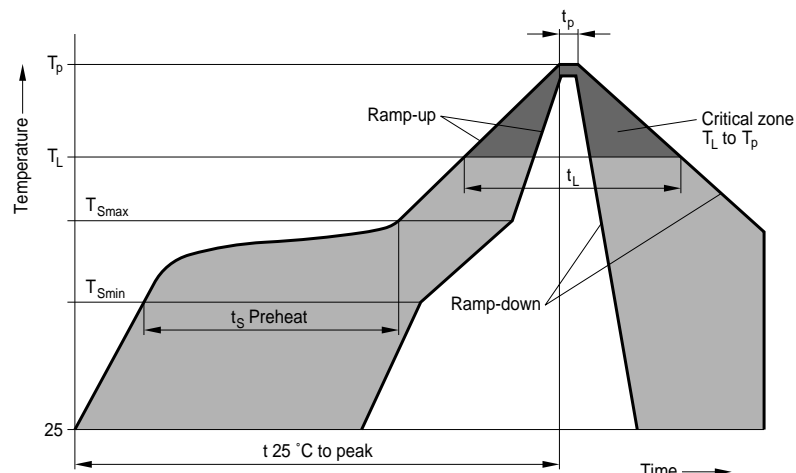
Recommended solder pad

Dimensions in mm

Symbol	Dim.
A	0.7
B	1.0
C	1.4
E	0.95



Recommended infrared reflow soldering temperature profile



Profile feature	Sn-Pb eutectic assembly	Pb-free assembly
Average ramp-up rate (T_{Smax} to T_p)	3 °C/ second max.	3 °C/ second max.
Preheat		
- Temperature min (T_{Smin})	100 °C	150 °C
- Temperature max (T_{Smax})	150 °C	200 °C
- Time (t_{Smin} to t_{Smax})	60 ... 120 seconds	60 ... 180 seconds
Time maintained above		
- Temperature min (T_L)	183 °C	217 °C
- Time (t_L)	60 ... 150 seconds	60 ... 150 seconds
Peak classification temperature (T_p)	220 °C ... 240 °C	240 °C ... 260 °C
Time within 5 °C of actual peak temperature (t_p)	10 ... 30 seconds	20 ... 40 seconds
Ramp-down rate	6 °C/ second max.	6 °C/ second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note: All temperatures refer to topside of the package, measured on the package body surface.

Soldering guidelines

The usage of mild, non-activated fluxes for soldering is recommended, as well as proper cleaning of the PCB.

The components are suitable for reflow soldering to JEDEC J-STD-020C.

Storage conditions

As far as possible, the components shall be employed within 12 months. They should be left in their original packing to avoid soldering problems due to oxidized contacts.

Storage temperature: -25 °C up to 45 °C

Relative humidity: < 75 % annual average, < 95 % on max. 30 days in a year.

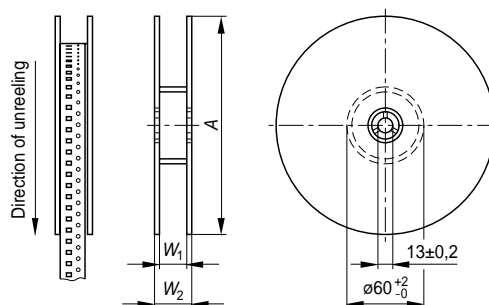
Reel dimensions in mm

Definition	Symbol	Dim.	Tolerance
Reel diameter	A	180	+0/ -3
Reel width (inside)	W ₁	8.4	+1.5/ -0
Reel width (outside)	W ₂	14.4	max.

Package: 8-mm tape

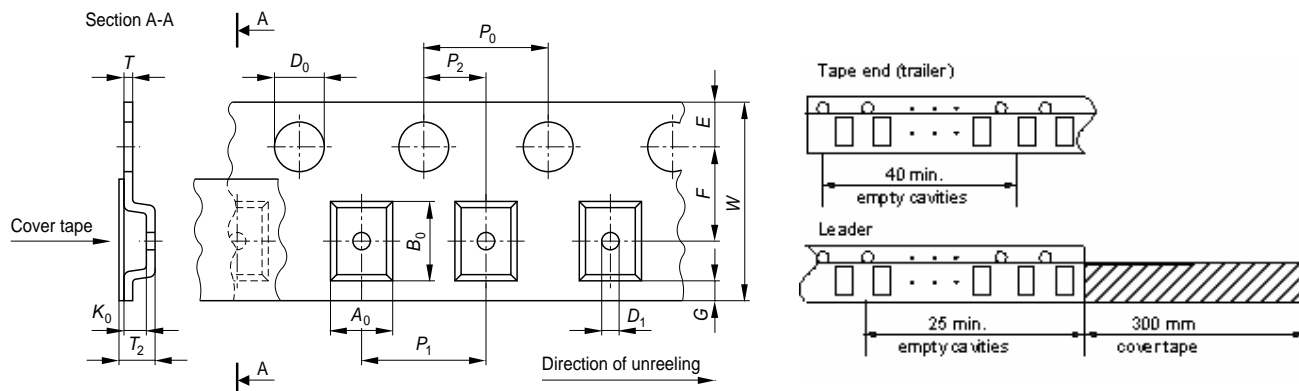
Reel material: Plastic

Packing unit: 2000 pcs. / reel



Taping to IEC 60286-3

Tape material: Blister



Dimensions and tolerances in mm:

Definition	Symbol	Dim.	Tolerance
Compartment width	A ₀	2.8	± 0.2
Compartment length	B ₀	3.5	± 0.2
Compartment height	K ₀	1.8	max.
Sprocket hole diameter	D ₀	1.5	+0.1/ -0
Compartment hole diameter	D ₁	1.0	min.
Sprocket hole pitch	P ₀	4.0	± 0.1 ¹⁾
Distance centre hole to centre compartment	P ₂	2.0	± 0.05
Pitch of the component compartments	P ₁	4.0	± 0.1
Tape width	W	8.0	± 0.3
Distance edge to centre of hole	E	1.75	± 0.1
Distance centre hole to centre compartment	F	3.5	± 0.05
Distance compartment to edge	G	0.75	min.
Thickness tape	T	0.3	max.
Overall thickness	T ₂	2.5	max.

1) $\leq \pm 0.2$ mm over any 10 pitches

Note

CeraDiodes are not suitable for switching applications or for voltage stabilization, where static power dissipation is required.

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